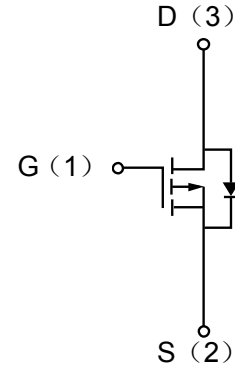


Description

The enhancement mode MOS is extremely high density cell and low on-resistance.

| MOSFET Product Summary | | |
|------------------------|-----------------------------|--------------------|
| V _{DS} (V) | R _{DS(on)} (mΩ) | I _D (A) |
| -20 | 28 @ V _{GS} =-4.5V | -4.5 |
| | 38 @ V _{GS} =-2.5V | |


Absolute maximum rating@25°C

| Rating | | Symbol | Value | Units |
|--|-----------------------|--------------------|------------|-------|
| Drain-Source Voltage | | V _{DS} | -20 | V |
| Gate-Source Voltage | | V _{GS} | ±12 | V |
| Drain Current | Continuous | I _D * | -4.5 | A |
| | 300μs Pulsed | | | |
| Diode Continuous Forward Current | | I _S * | -1 | A |
| Total Power Dissipation | T _A =25°C | P _D * | 0.83 | W |
| | T _A =100°C | | 0.3 | W |
| Maximum Junction Temperature | | T _J | 150 | °C |
| Storage Temperature Range | | T _{STG} | -55 to 150 | °C |
| Thermal Resistance-Junction to Ambient | | R _{θJA} * | 150 | °C/W |

Note:

*Surface Mounted on 1in² pad area, t≤10sec.

Electrical characteristics per line@25°C (unless otherwise specified)

| Parameter | Symbol | Conditions | Min. | Typ. | Max. | Units |
|---|----------------|--|------|------|-----------|------------|
| Static Characteristics | | | | | | |
| Drain-Source Breakdown Voltage | BV_{DSS} | $I_D = -250\mu A, V_{GS} = 0V$ | -20 | - | - | V |
| Zero Gate Voltage Drain Current | I_{DSS} | $V_{DS} = -16V, V_{GS} = 0V$ | - | - | -1 | A |
| Gate-Body Leakage Current | I_{GSS} | $V_{DS} = 0V, V_{GS} = \pm 12V$ | - | - | ± 100 | nA |
| Gate Threshold Voltage | $V_{GS(th)}$ | $V_{DS} = V_{GS}, I_D = -250\mu A$ | -0.5 | -0.7 | -1 | V |
| Static Drain-Source On-Resistance | $R_{DS(on)}^a$ | $V_{GS} = -4.5V, I_D = -4.5A$ | - | 28 | 35 | m Ω |
| | | $V_{GS} = -2.5V, I_D = -2.5A$ | - | 38 | 50 | |
| | | $V_{GS} = -1.8V, I_D = -2.0A$ | | 55 | 75 | |
| Diode Forward Voltage | V_{SD}^a | $V_{GS} = 0V, I_{SD} = -1A$ | | -0.7 | -1.3 | V |
| Gate Charge Characteristics ^b | | | | | | |
| Total Gate Charge | Qg | $V_{DS} = -10V, V_{GS} = -4.5V,$ $I_{DS} = -4.5V$ | | 14 | 20 | nC |
| Gate-Source Charge | Qgs | | | 2.1 | | |
| Gate-Drain Charge | Qgd | | | 4.7 | | |
| Dynamic Characteristics ^b | | | | | | |
| Gate Resistance | R_G | $V_{GS} = 0V, V_{DS} = 0V, F = 1MHz$ | | 7 | | Ω |
| Input Capacitance | C_{iss} | $V_{GS} = 0V, V_{DS} = -10V,$ $F = 1MHz$ | | 1520 | | pF |
| Output Capacitance | C_{oss} | | | 225 | | |
| Reverse Transfer Capacitance | C_{rss} | | | 165 | | |
| Turn-On Delay Time | $t_{d(on)}$ | $V_{DD} = -10V, V_{GEN} = -4.5V,$ $R_L = 10\Omega, R_G = 6\Omega,$ $I_D = -1A$ | - | 6 | 12 | ns |
| Turn-off Rise Time | t_r | | | 13 | 24 | |
| Turn-Off Delay Time | $t_{d(off)}$ | | - | 86 | 156 | |
| Turn-off Fall Time | t_f | | | 42 | 77 | |
| Reverse Recovery Time | t_{rr} | $I_{SD} = -4.5A, dI_{SD}/dt = 100A/\mu s$ | | 21 | | ns |
| Reverse Recovery Charge | q_{rr} | | | 9 | | nC |

Note:

a: Pulse test; pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.

b: Guaranteed by design, not subject to production testing.

Typical Characteristics

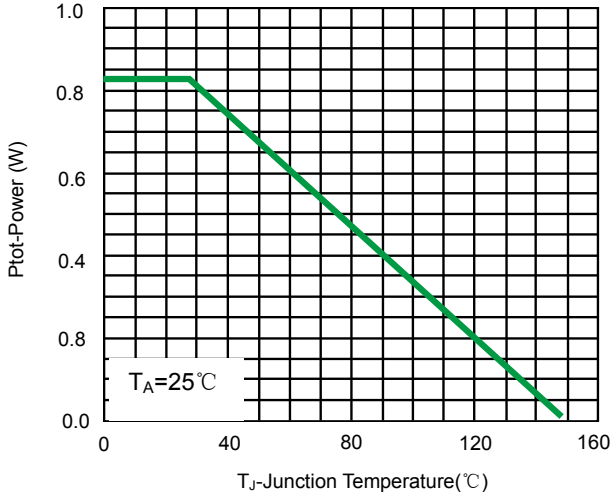


Fig 1. Power Dissipation

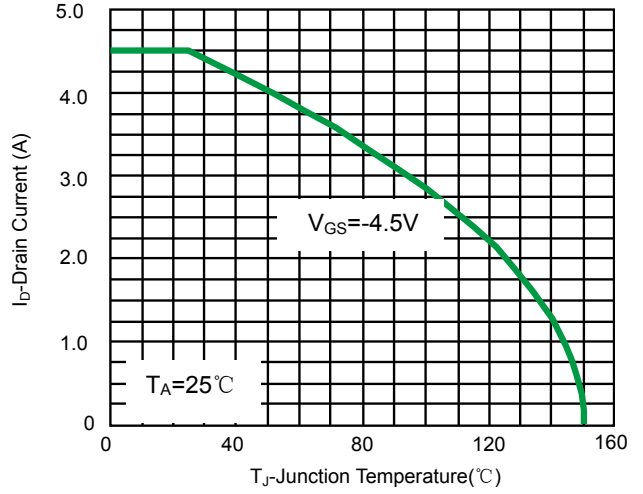


Fig 2. Drain Current

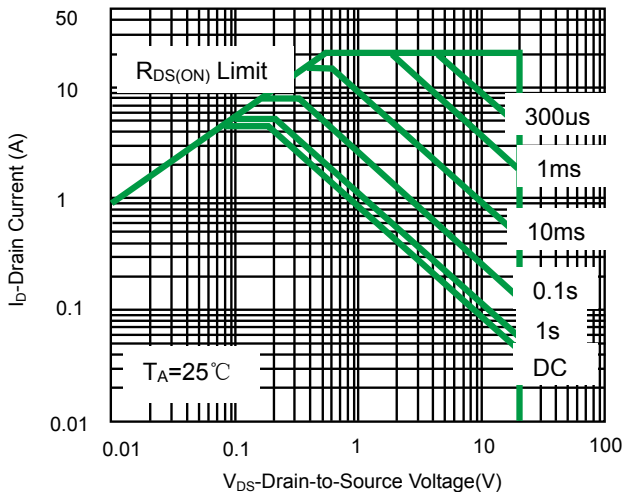


Fig 3. Safe Operation Area

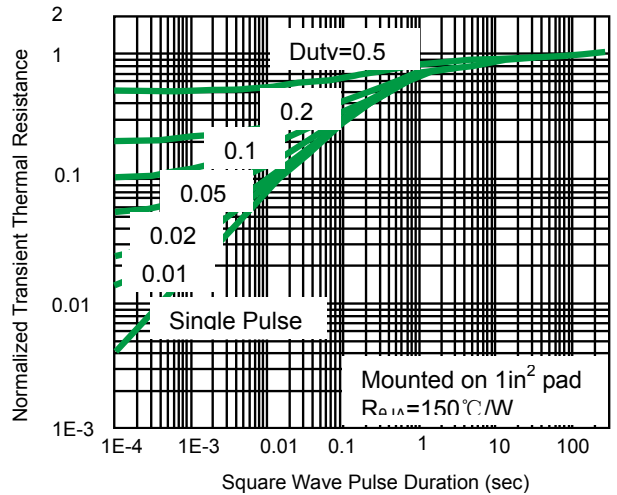


Fig 4. Thermal Transient Impedance

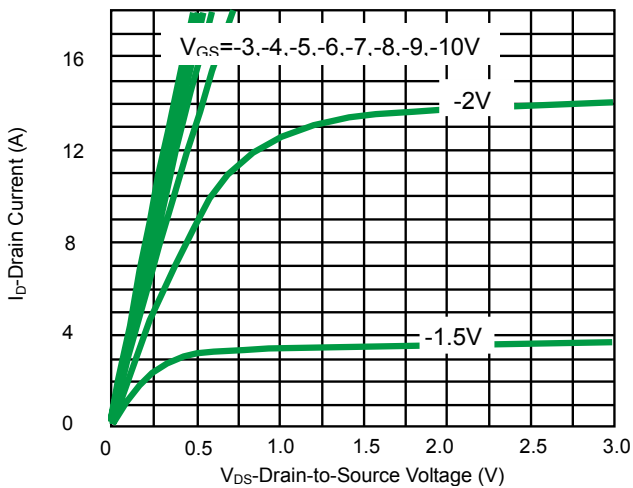


Fig 5. Output Characteristics

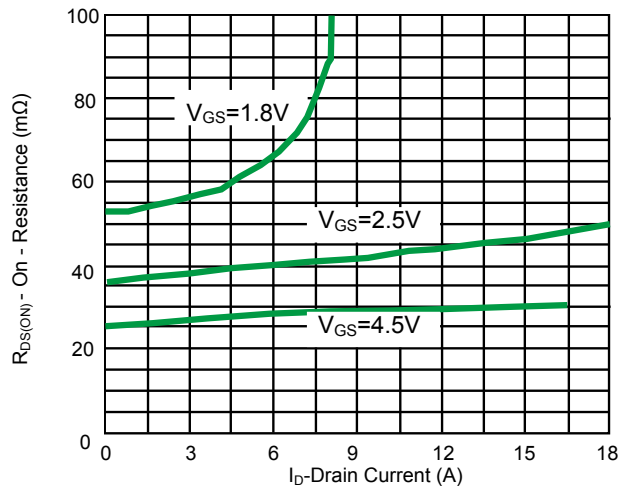


Fig 6. Drain-Source On Resistance

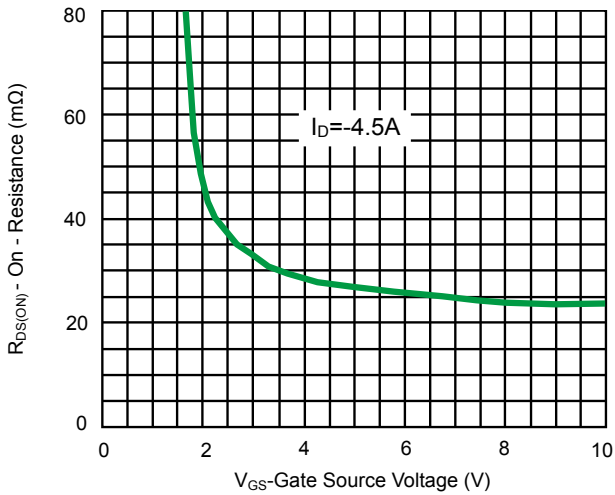


Fig 7. Drain-Source On Resistance

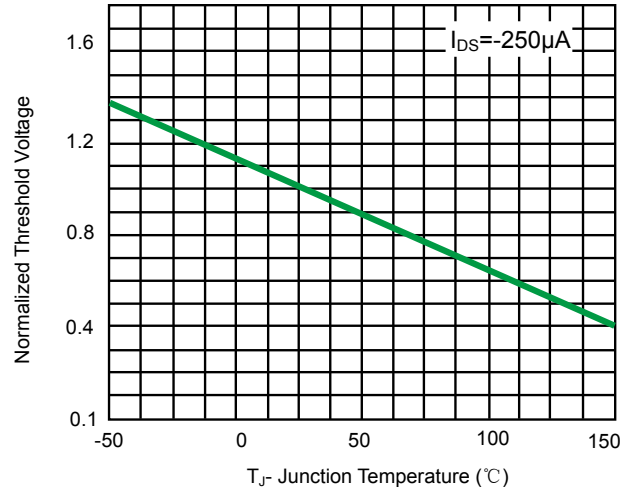


Fig 8. Gate Threshold Voltage

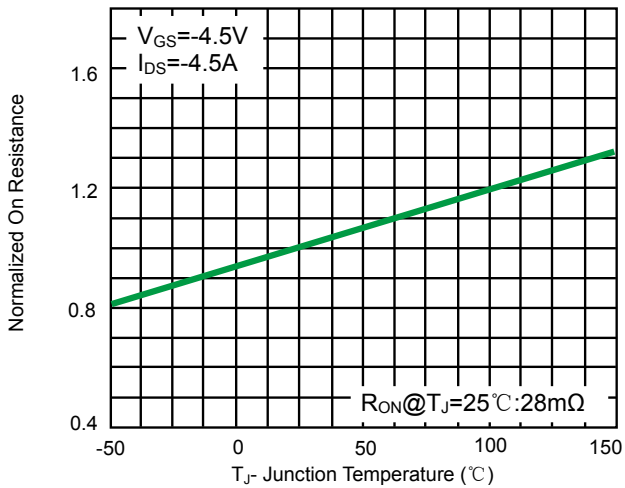


Fig 9. Drain-Source On Resistance

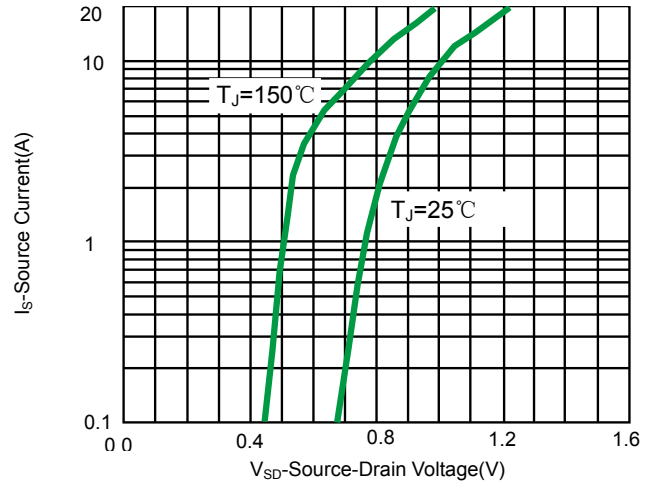


Fig 10. Source-Drain Diode Forward

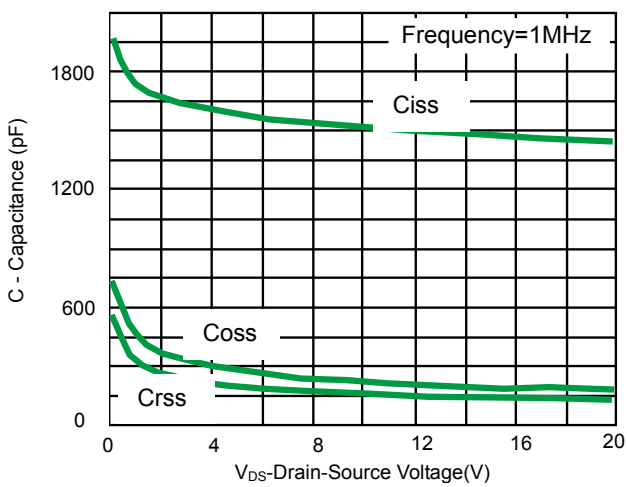


Fig 11. Capacitance

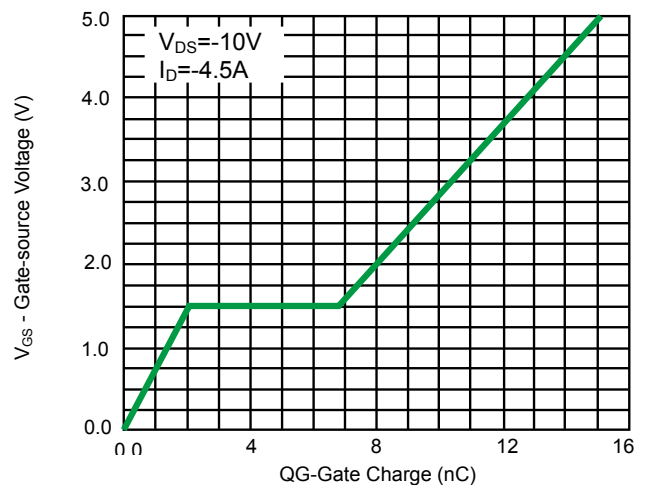
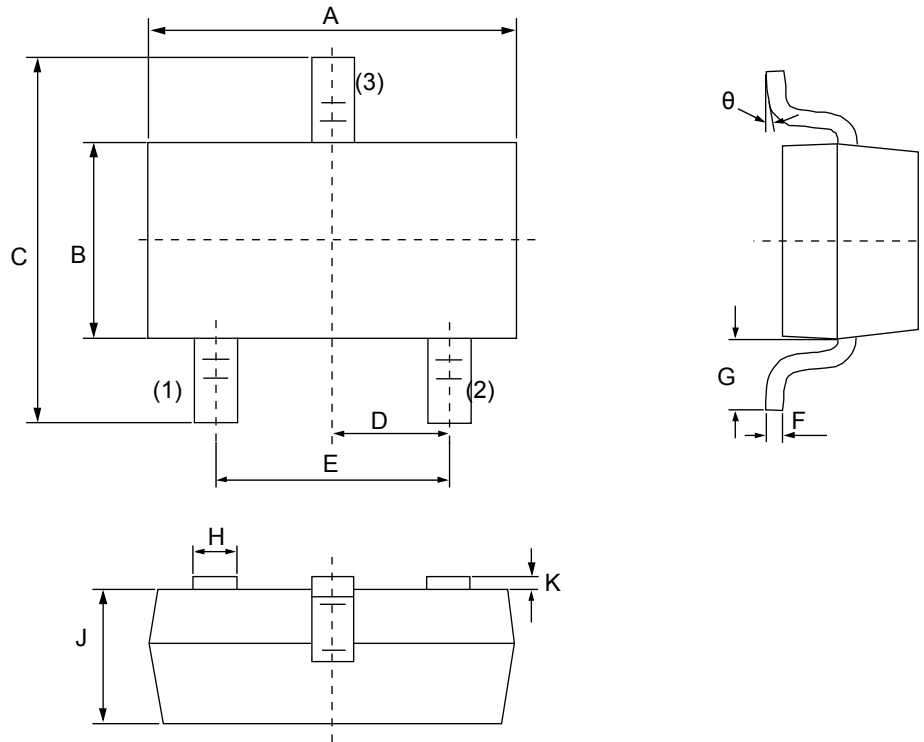



Fig 12. Gate Charge

Product dimension(SOT-23-3L)



| Dim | Millimeters | | Inches | |
|----------|-------------|------|------------|-------|
| | MIN | MAX | MIN | MAX |
| A | 2.82 | 3.02 | 0.111 | 0.119 |
| B | 1.50 | 1.70 | 0.059 | 0.067 |
| C | 2.65 | 2.95 | 0.104 | 0.116 |
| D | 0.950(BSC) | | 0.037(BSC) | |
| E | 1.80 | 2.00 | 0.071 | 0.079 |
| F | 0.10 | 0.20 | 0.004 | 0.008 |
| G | 0.55(REF) | | 0.022(REF) | |
| H | 0.30 | 0.50 | 0.012 | 0.020 |
| J | 1.05 | 1.15 | 0.041 | 0.045 |
| K | 0.00 | 0.10 | 0.000 | 0.004 |
| θ | 0° | 8° | 0° | 8° |


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